
FINAL PRODUCT/PROCESS CHANGE NOTIFICATION #16970

Generic Copy

Issue Date: 05-Mar-2013

TITLE: Final Notification of additional Test and Tape & Reel site for flip-chip CSP from ON Semiconductor Seremban, Malaysia to existing external manufacturing site, JCAP, China**.**

PROPOSED FIRST SHIP DATE: 05-Jun-2013 or earlier upon customer approval

AFFECTED CHANGE CATEGORY(S): ON Semiconductor Test and Tape & Reel

FOR ANY QUESTIONS CONCERNING THIS NOTIFICATION:
Contact your local ON Semiconductor Sales Office or Kai Loong Lai <ffyj9h@onsemi.com>

SAMPLES: Contact your local ON Semiconductor Sales Office

ADDITIONAL RELIABILITY DATA: NA

NOTIFICATION TYPE:

Final Product/Process Change Notification (FPCN)

Final change notification sent to customers. FPCNs are issued at least 90 days prior to implementation of the change.

ON Semiconductor will consider this change approved unless specific conditions of acceptance are provided in writing within 30 days of receipt of this notice. To do so, contact <quality@onsemi.com>.

DESCRIPTION AND PURPOSE:

ON Semiconductor is notifying customers of its plan to have an additional Test and Tape & Reel site of flip-chip CSP from ON Semiconductor Seremban, Malaysia to an existing external manufacturing site, Jiangyin Changdian Advanced Packaging, China (JCAP).

Jiangyin Changdian Advanced Packaging, China (JCAP) is an existing external manufacturing site that is ISO/TS16949, ISO-9001 and ISO-14001 certified.

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RELIABILITY DATA SUMMARY:

N/A

ELECTRICAL CHARACTERISTIC SUMMARY:

Available upon request

CHANGED PART IDENTIFICATION:

Affected product from ON Semiconductor with date code 1320 representing WW20, 2013 and greater may be sourced from either Seremban (Malaysia) or JCAP (China) site.

List of affected General Parts:

NUF2441FCT1G